

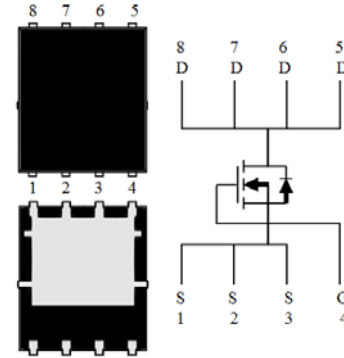
30V N-Channel MOSFET
Applications:

- DC-DC Converters
- Motor Bridge Switch
- OringFET/Load Switching

V_{DS}	$R_{DS(ON)}(MAX)$	I_D
30V	1.9m Ω	32A

Features:

- Lead Free
- Low $R_{DS(ON)}$ to Minimize Conductive Loss
- Low Gate Charge for Fast Switching Application
- Optimized $V_{(BR)DSS}$ Ruggedness



PowerPAK Pin Definition and Inner Circuit

Ordering Information

Park Number	Package	Brand
MXP31P9SG	PowerPAK	MXP

Absolute Maximum Ratings
 $T_C=25^{\circ}C$ unless otherwise specified

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-to-Source Voltage	30	V
I_D	Continuous Drain Current	$V_{GS}=10V, T_C=25^{\circ}C$	151
		$V_{GS}=10V, T_A=25^{\circ}C$	32
I_{DM}	Pulsed Drain Current @ $V_{GS}=10V$	191	
P_D	Power Dissipation	$T_C=25^{\circ}C$	78
		$T_A=25^{\circ}C$	2.5
V_{GS}	Gate-to-Source Voltage	+/-20	V
T_J and T_{stg}	Operating Junction and Storage Temperature Range	-55 to 150	$^{\circ}C$

Thermal Resistance

Symbol	Parameter	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.6	$^{\circ}C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	50	$^{\circ}C/W$

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OFF Characteristics
 $T_J=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	30	-	-	V	$V_{GS}=0\text{V}$, $I_D=1\text{mA}$
I_{DSS}	Drain-to-Source Leakage Current	-	-	1	uA	$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$
		-	-	100		$V_{DS}=24\text{V}$, $V_{GS}=0\text{V}$, $T_J=125^{\circ}\text{C}$
I_{GSS}	Gate-to-Source Forward Leakage	-	-	100	nA	$V_{GS}=+20\text{V}$
	Gate-to-Source Reverse Leakage	-	-	100		$V_{GS}=-20\text{V}$

ON Characteristics
 $T_J=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	-	1.4	1.9	m Ω	$V_{GS}=10\text{V}$, $I_D=32\text{A}$
		-	1.8	2.4		$V_{GS}=4.5\text{V}$, $I_D=32\text{A}$
$V_{GS(th)}$	Gate Threshold Voltage	1.2	-	2.5	V	$V_{GS}=V_{DS}$, $I_D=1\text{mA}$

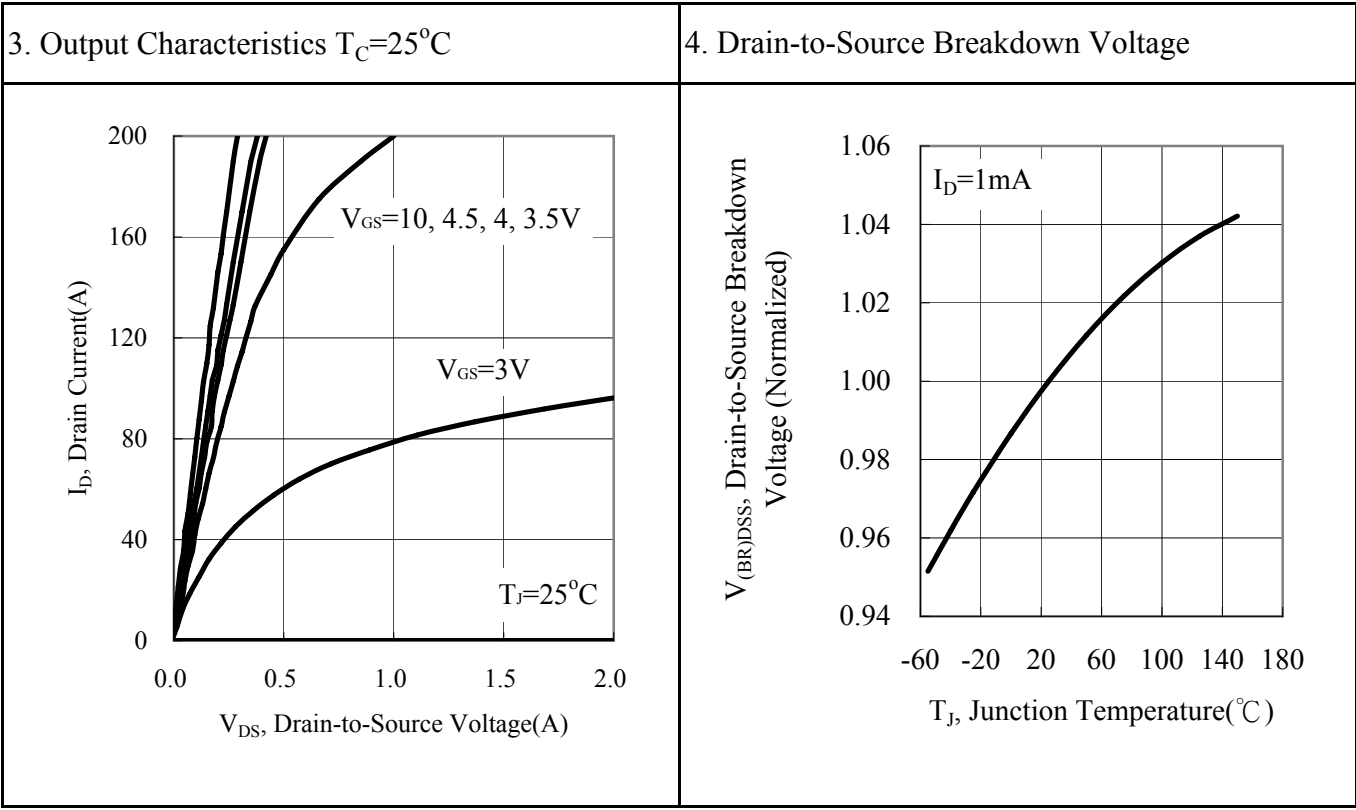
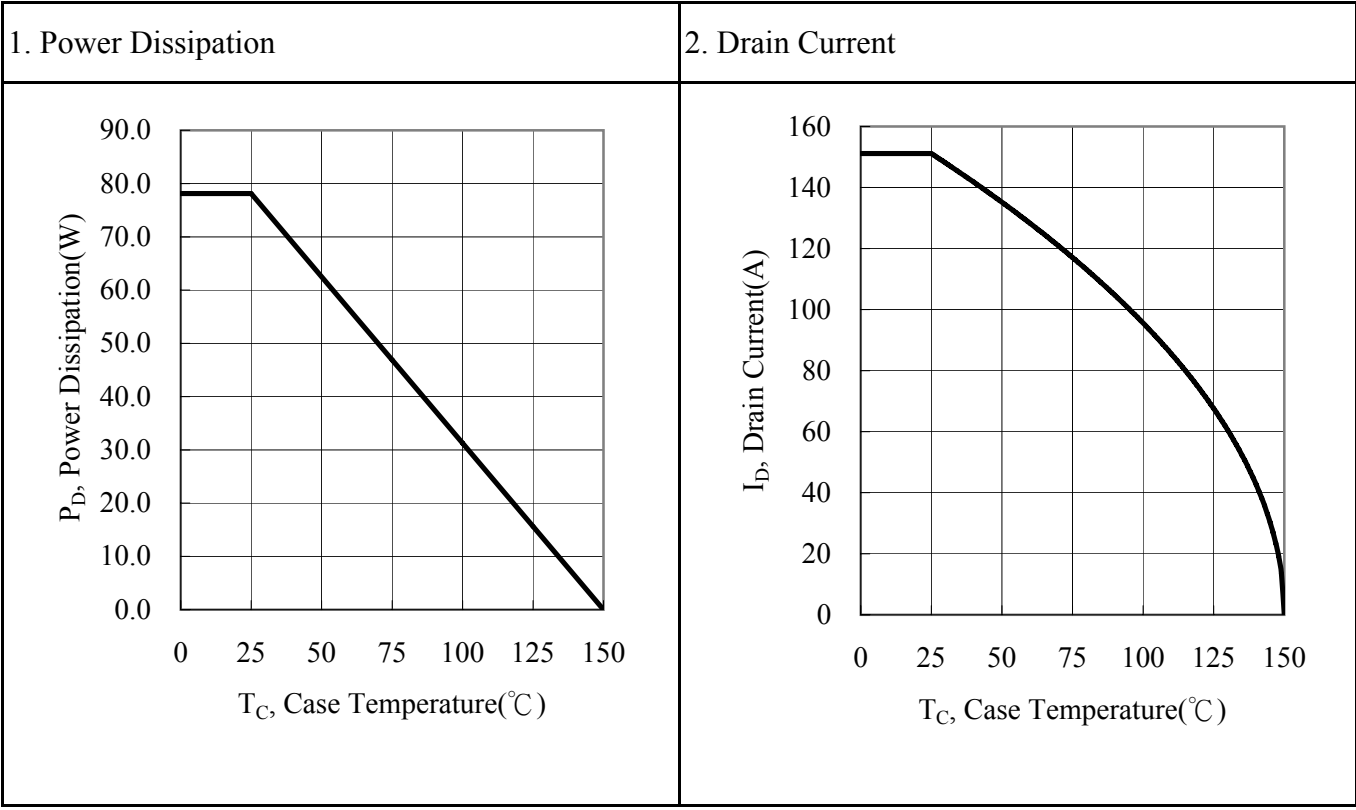
Dynamic Characteristics
 $T_J=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions	
C_{iss}	Input Capacitance	-	2580	-	pF	$V_{GS}=0\text{V}$, $V_{DS}=15\text{V}$, $f=1.0\text{MHz}$	
C_{oss}	Output Capacitance	-	740	-			
C_{rss}	Reverse Transfer Capacitance	-	210	-			
Q_g	Total Gate Charge	-	42.8	-	nC	$V_{DD}=15\text{V}$, $I_D=32\text{A}$	
		-	19.6	-			$V_{GS}=10\text{V}$
Q_{gs}	Gate-to-Source Charge	-	11.6	-			$V_{GS}=4.5\text{V}$
Q_{gd}	Gate-to-Drain ("Miller") Charge	-	6.7	-			
$T_d(on)$	Turn-on Delay Time	-	21.8	-	ns	$V_{DD}=15\text{V}$, $I_D=16\text{A}$, $V_{GS}=10\text{V}$, $R_G=10\Omega$, $R_L=0.94\Omega$	
T_r	Rise Time	-	15.6	-			
$T_d(off)$	Turn-off Delay Time	-	74.6	-			
T_f	Fall Time	-	28.5	-			
R_g	Gate Resistance	-	1.4	-	Ω		

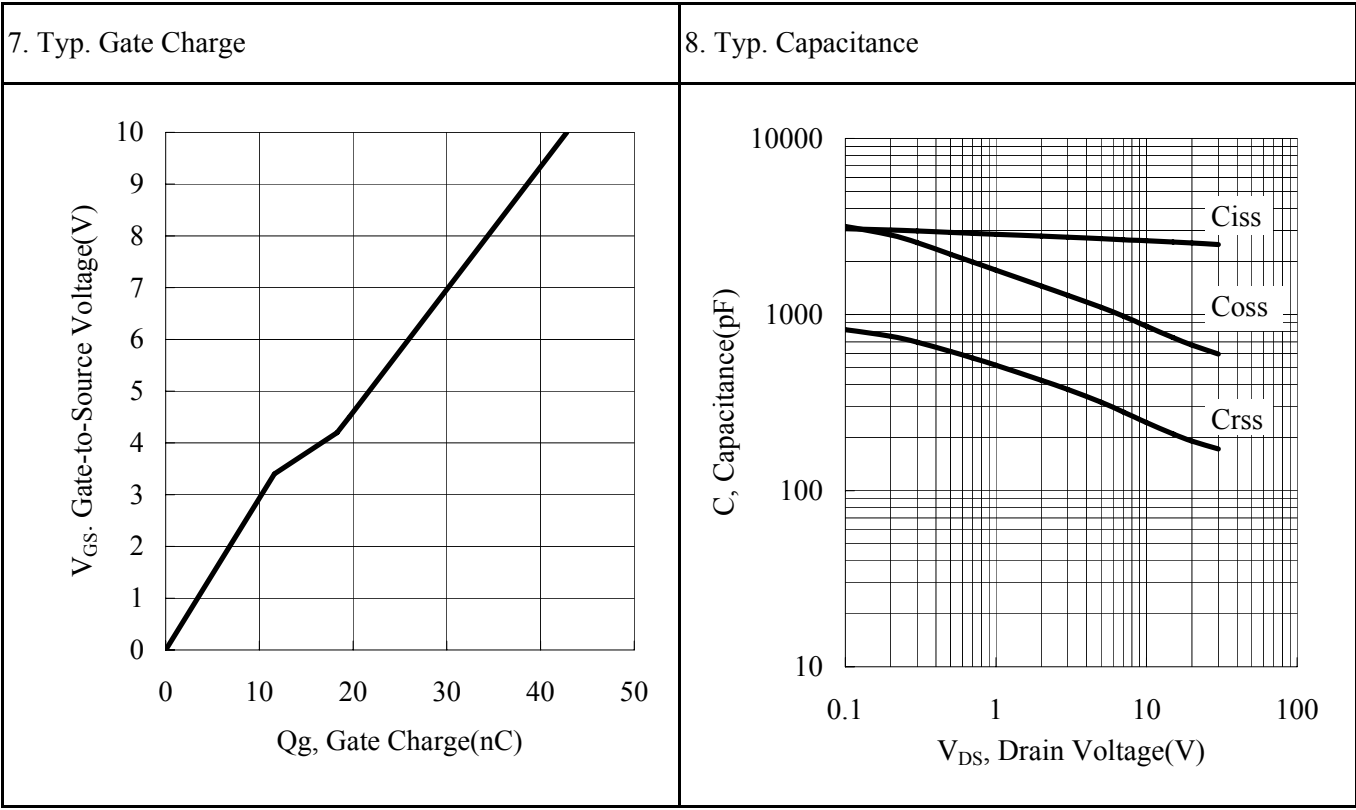
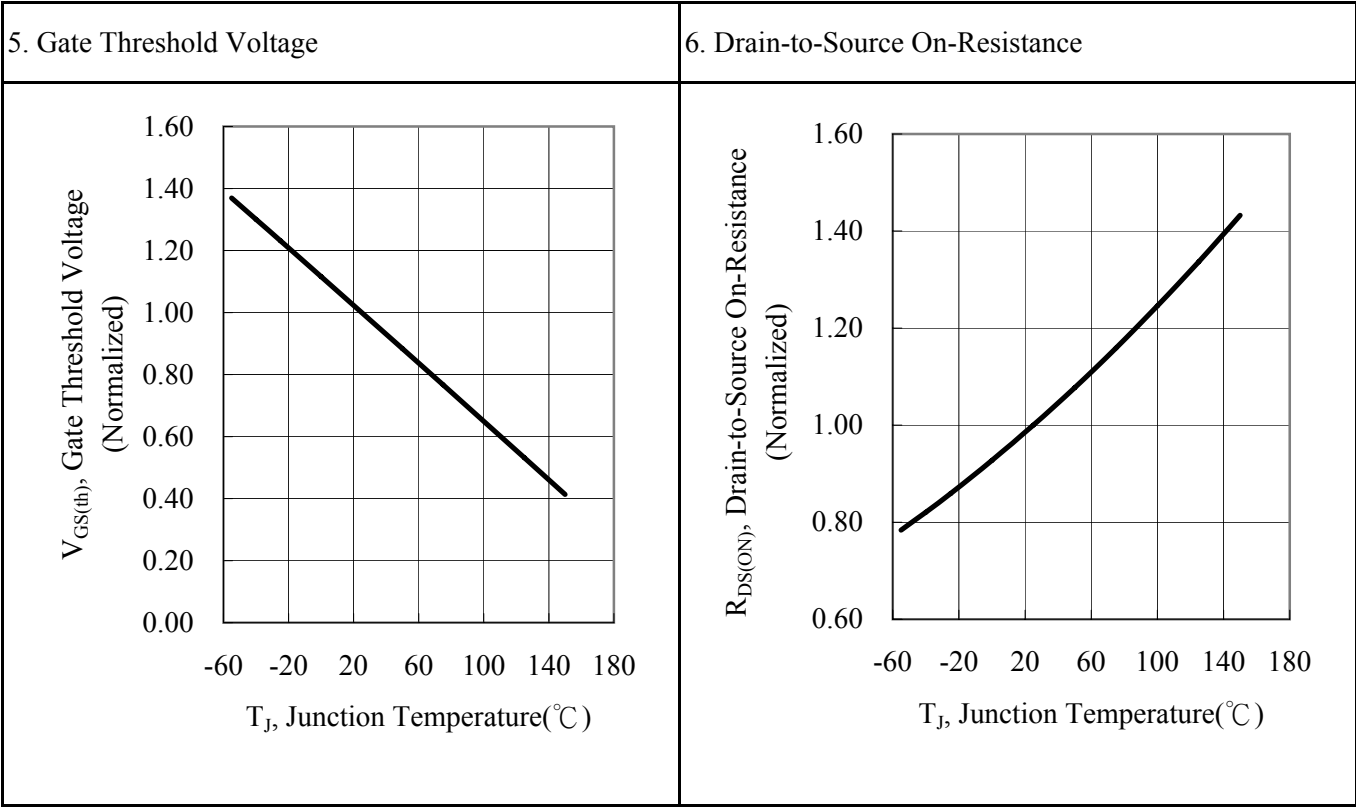
Source-Drain Diode Characteristics
 $T_J=25^{\circ}\text{C}$ unless otherwise specified

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{SD}	Diode Forward Voltage	-	-	1.2	V	$I_S=32\text{A}$, $V_{GS}=0\text{V}$
T_{rr}	Reverse Recovery Time	-	37.8	-	ns	$I_S=32\text{A}$, $di/dt=100\text{A}/\mu\text{s}$
Q_{rr}	Reverse Recovery Charge	-	35.2	-	nC	

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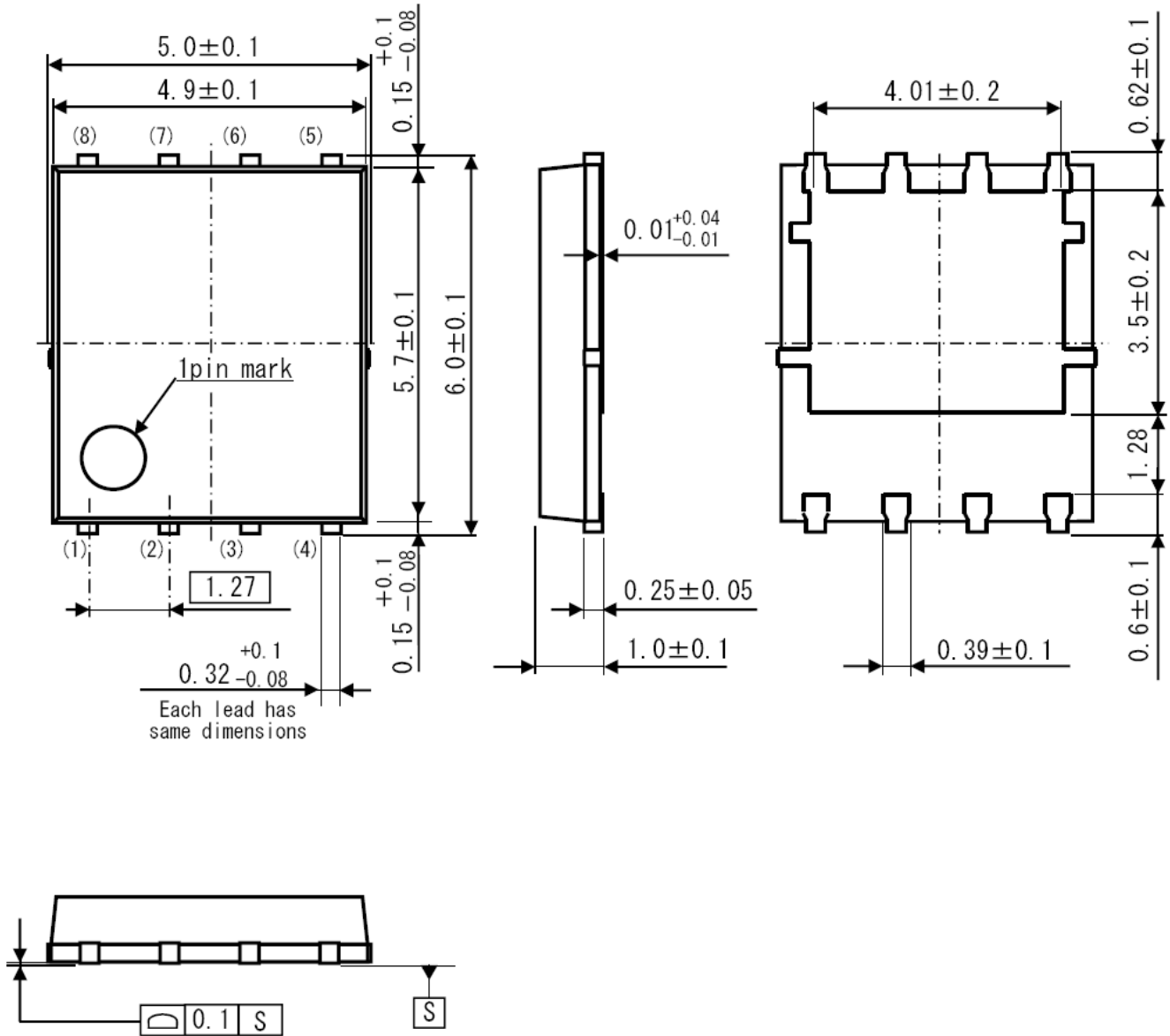


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PowerPAK

1. Outline Dimension



UNIT : mm

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